

What is claimed is:

1. A titanium copper alloy having excellent strength and bendability characterized in that;
5 it comprises 1.0 to 4.5% by mass of Ti, the balance of copper and inevitable impurities,; diameters of intermetallic compound particles consisting of Cu and Ti precipitated in the alloy are 3 μm or less; the average number of said intermetallic compound particles having the
10 diameters of 0.2 to 3 μm is 700 or less per a cross-sectional area of 1000 μm^2 in a transverse direction to a rolling direction; the average grain size measured in a cross-sectional area in a transverse direction to a rolling direction is 10 μm or less; and a tensile strength is 890 MPa or more.
- 15 2. The titanium copper alloy according to claim 1, wherein the average number of the intermetallic compound particles having the diameters of 0.2 to 3 μm is 6 to 700 per a cross-sectional area of 1000 μm^2 in a transverse direction to a rolling direction.
3. A manufacturing method of the titanium copper alloy according
20 to claim 1 or 2 comprising a hot rolling, a cold rolling, a solution treatment, a cold rolling and an aging treatment, of a titanium copper alloy ingot in this order characterized in that; the ingot is heated at a temperature of 850 to 950 °C for 30 minutes or more before the hot rolling and then the ingot is hot rolled and the
25 temperature in the end of the hot rolling is 700 °C or more; in the solution treatment, the material is annealed at a temperature in a

range between $(T-50)$ °C and $(T+10)$ °C, wherein T is a temperature at which the solubility of Ti in Cu is equal to the concentration of Ti contained in the alloy; and thereafter

the annealed material is cooled at a cooling rate of 100 °C/sec or more.

5 4. A manufacturing method of the titanium copper alloy according to claim 3, wherein a reduction ratio in the cold rolling between the solution treatment and the aging treatment is 50% or less.

5. A manufacturing method of the titanium copper alloy according to claim 3 or 4, wherein the aging treatment is conducted at a
10 temperature of 300 to 600°C.